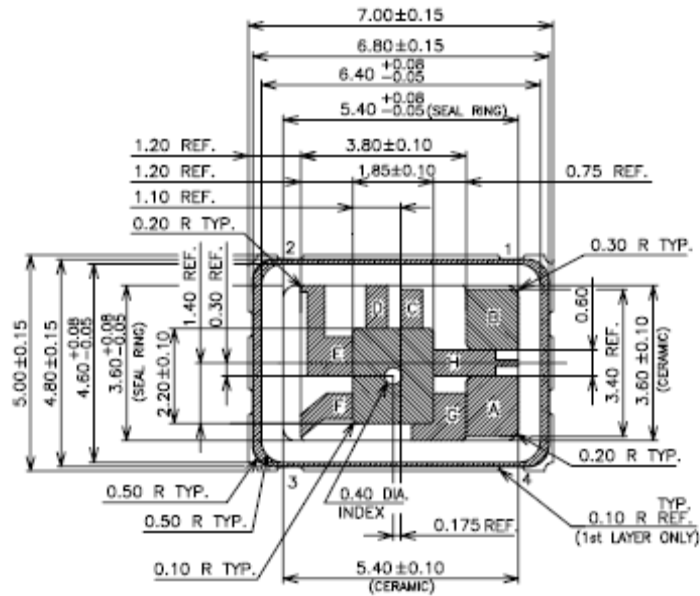


## PRODUCT CHANGE NOTIFICATION

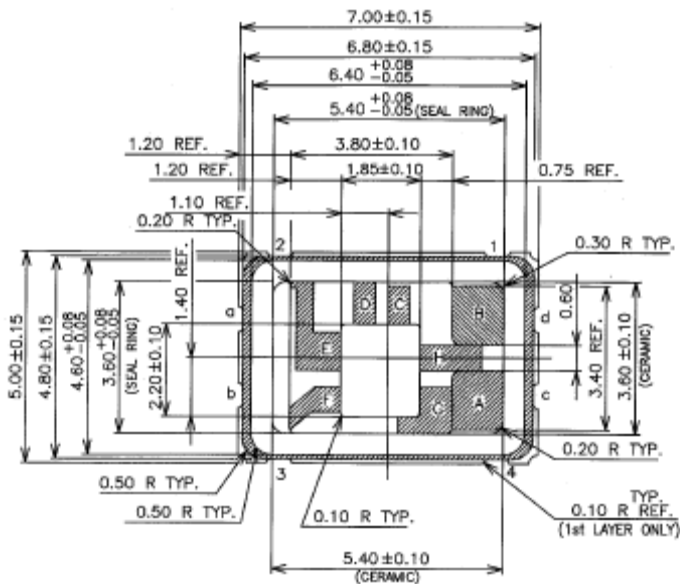
Title	Alternate Package for 5 x 7mm CMOS Oscillator																																										
Keywords	Product Change Notification, SM77 series CMOS Oscillators																																										
Article:	<p>Pletronics Inc. is committed to providing the highest quality devices on time to meet our customer’s requirements. During the past year market conditions have lead to an increase in the lead times of the suppliers of ceramic packages. In an effort to remain responsive to the needs of our customers Pletronics Inc. would like to add an additional ceramic package type to the Pletronics Product Family.</p> <p>The current ceramic package and the proposed addition are both manufactured by the same company. The manufacturing location, assembly materials, plating thickness and composition remain the same. The changes mainly concern the location and routing of traces in the package.</p> <p>Material and Plating for both packages:</p> <p><b>Materials</b></p> <p>Pad Plating Material Ni    1.27~8.89um    Thickness Au    0.3~1.0um      Thickness</p> <p>Ceramic Material</p> <table><tr><th></th><th colspan="2">ELECTRICAL</th><th colspan="2">THERMAL</th><th colspan="3">MECHANICAL</th></tr><tr><th></th><th colspan="2">Dielectric Constant</th><th colspan="2">Dissipation Factor (x10E-4)</th><th>CTE(ppm/K) (RT-400°C)</th><th>Thermal Conductivity (W/mK)</th><th>Flexural Strength (MPa)</th><th>Young's Modulus of Elasticity (GPa)</th></tr><tr><th></th><th>1MHz</th><th>2 GHz</th><th>1MHz</th><th>2 GHz</th><th></th><th></th><th></th><th></th></tr><tr><td>Al2O3</td><td>9.6</td><td>—</td><td>5</td><td>—</td><td>6.9</td><td>18</td><td>460</td><td>310</td></tr></table>									ELECTRICAL		THERMAL		MECHANICAL				Dielectric Constant		Dissipation Factor (x10E-4)		CTE(ppm/K) (RT-400°C)	Thermal Conductivity (W/mK)	Flexural Strength (MPa)	Young's Modulus of Elasticity (GPa)		1MHz	2 GHz	1MHz	2 GHz					Al2O3	9.6	—	5	—	6.9	18	460	310
	ELECTRICAL		THERMAL		MECHANICAL																																						
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Layer by Layer comparison:

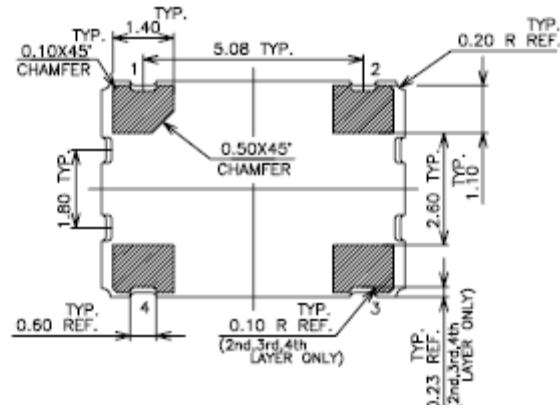
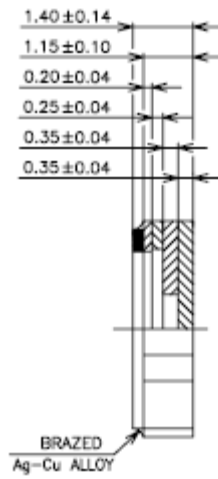
Current Package



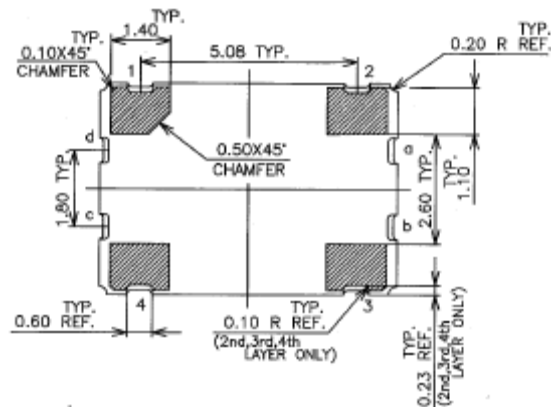
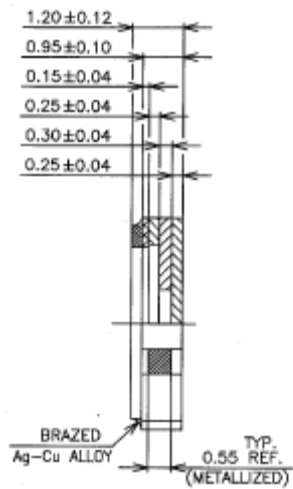
Alternate Package



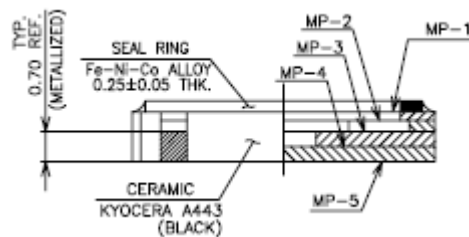
## Current Package



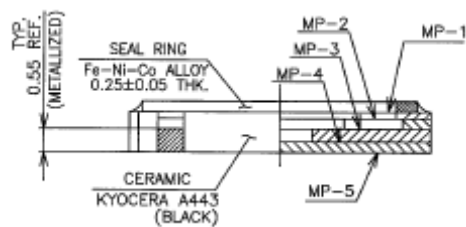
## Alternate Package

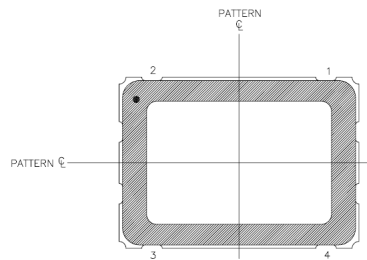


## Current Package

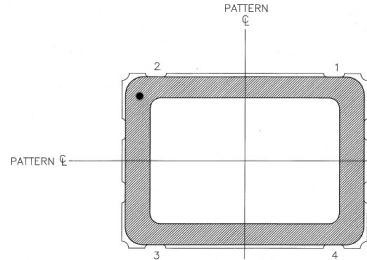


## Alternate Package

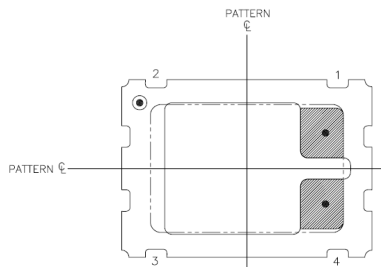




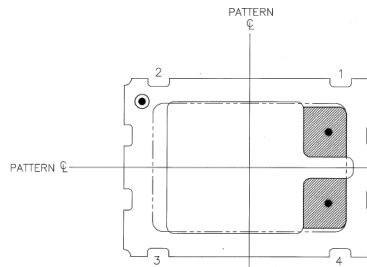
MP-1



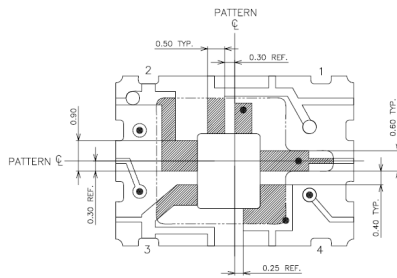
MP-1



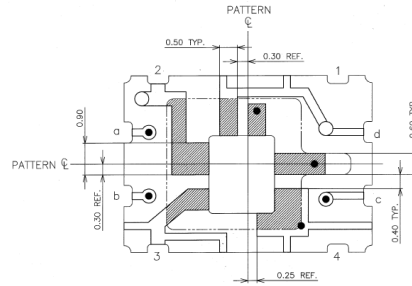
MP-2



MP-2

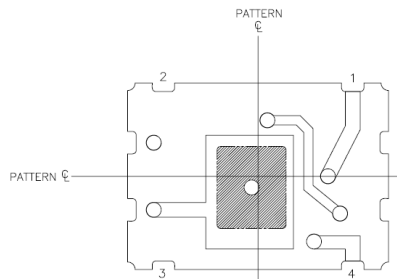


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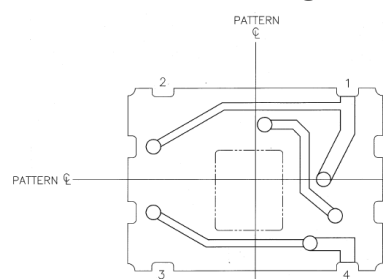


MP-3

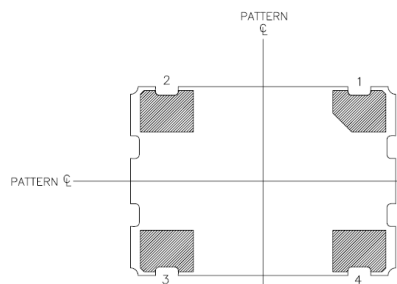
## Current Package



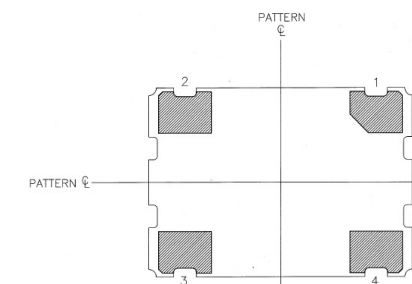
MP-4



MP-4



MP-5



MP-5

## Alternate Package

## Environmental Reliability Testing

### Bond Strength

**Test:** Bond Strength  
MIL-STD-883

**Standard** M2011 Test Condition C

**Date:** 9/6/2010

Qualification Status PASSED

#### Device Information:

Lot	DUT #	Part #	Date Code
Lot 1	1 to 5	SM77	0HB-SFLT
Lot 2	6 to 10	SM77	0HG-SFLT
Lot 3	11 to 15	SM77	0J6-SFLT

\* Test equipment : Mark-10 EG

\* Gold wire(diameter) : 1mil, degree of purity: 99.99%

Unit : gf

Lot no.	DUT	Wire pull test					
		P1	P2	P3	P4	P5	P6
0HB-SFLT	1	7.2	8.1	9.4	8.4	9.2	9.1
	2	9.4	9.6	8.7	9.4	8.6	8.4
	3	8.5	8.1	9.2	8.7	8.4	9
	4	9.1	9.6	9.1	8.5	9.3	9.5
	5	10.2	8.1	8.9	8.4	9.3	9.2
0HG-SFLT	6	8	8.8	8.1	8.6	9.4	10.1
	7	9.2	9.7	9.4	8.1	8.3	9.5
	8	10.2	10.6	10.4	9.8	10.3	10.5
	9	9.1	9.6	9.4	8.6	8.2	9.3
	10	9.5	9	9.3	10.5	8.7	9.1
0J6-SFLT	11	10	10.7	10.5	9.8	11	10.3
	12	10.8	10.9	10.4	10.6	9.7	10
	13	9.8	9.5	8.7	9.6	9.4	9.7
	14	10.8	10.3	10.7	9.9	9.7	10
	15	9.6	9.1	9.4	9.6	9.4	9.3

Failure category a-1 unless otherwise noted

## Die Shear Test

**Test:** Die Shear

**Standard** MIL-STD 883 method 2019

**Date:** 9/6/2010

Qualification Status

PASSED

### Device Information:

Lot	DUT #	Part #	Date Code
Lot 1	1 to 5	SM77	0HB-SFLT
Lot 2	6 to 10	SM77	0HG-SFLT
Lot 3	11 to 15	SM77	0J6-SFLT

### Die Dimensions

mm	in
0.75	0.02953
0.69	0.02717
Area in sq in	8.02E-04

### Failure Criteria (in Kg f)

0.3	`@ x1.0
0.4	`@ x 1.25
0.65	`@ x 2.0

Lot no.	DUT	Value(Kg f)
0HB-SFLT	1	1.841
	2	1.963
	3	2.108
	4	2.388
	5	2.169
0HG-SFLT	6	2.517
	7	1.912
	8	1.964
	9	2.149
	10	2.354
0J6-SFLT	11	2.451
	12	2.228
	13	2.415
	14	2.465
	15	2.129

## Leak Test

**Test:** Leak Check Gross and Fine

**Standard** MIL-STD-883 Method 1014 Cond. A1, C1

**Date:** 9/6/2010

Qualification Status

PASSED

### Device Information:

Lot	DUT #	Part #	Date Code
Lot 1	1 to 15	SM77	0HB-SFLT
Lot 2	16 to 30	SM77	0HG-SFLT
Lot 3	31 to 45	SM77	0J6-SFLT

**Fine Leak**

Test Conditions

He Bombing Soak time : 7200sec(2hrs), Bombing pressure : 75psi

Unit		atm.cc/sec	Reject Criteria	>5.00E-8	atm.cc/sec
Lot no.	DUT	Leak Rate			
Lot 1	1	1.40E-09			
	2	1.30E-09			
	3	1.50E-09			
	4	1.30E-09			
	5	1.20E-09			
	6	1.20E-09			
	7	1.20E-09			
	8	1.30E-09			
Lot 2	1	1.20E-09			
	2	1.30E-09			
	3	1.40E-09			
	4	1.10E-09			
	5	1.40E-09			
	6	1.20E-09			
	7	1.40E-09			
	8	1.20E-09			
Lot 3	1	1.10E-09			
	2	1.40E-09			
	3	1.10E-09			
	4	1.30E-09			
	5	1.10E-09			
	6	1.30E-09			
	7	1.20E-09			
	8	1.30E-09			

**Gross  
Leak**

Test Conditions

Bombing Soak time : 7200sec(2hrs), Bombing pressure : 75psi

Test solution, FC-40 temp: 125°C±5C

Lot no.	DUT	Result
Lot 1	1	Pass
	2	Pass
	3	Pass
	4	Pass
	5	Pass

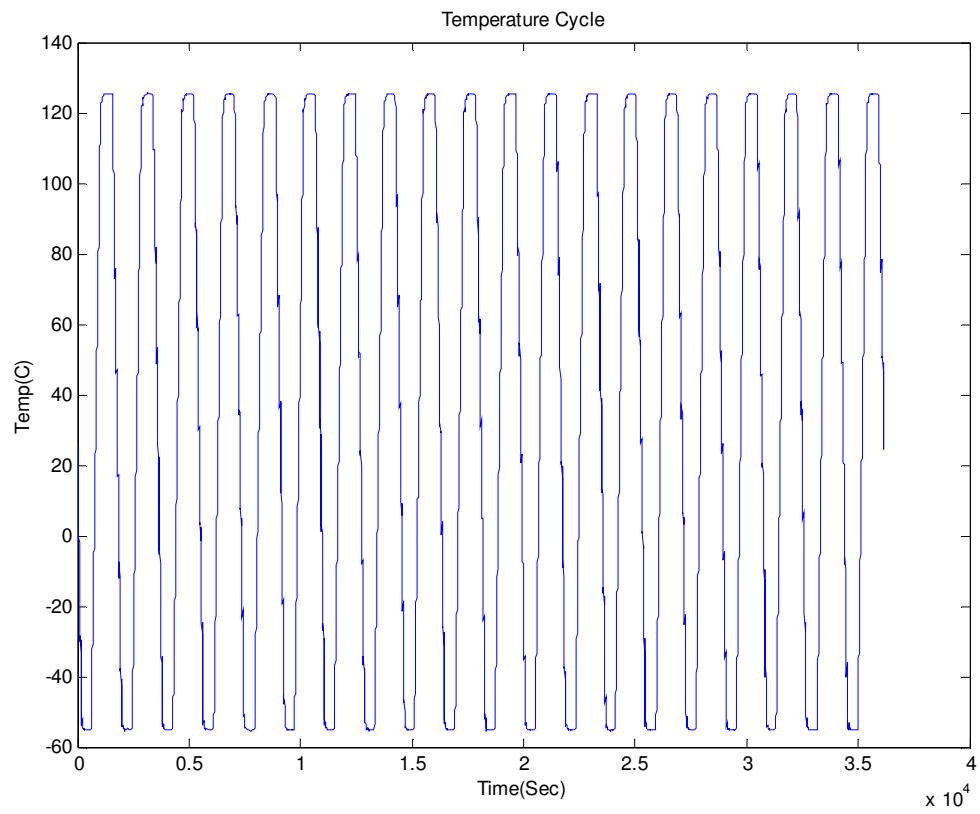
	6	Pass
	7	Pass
	8	Pass
Lot 2	1	Pass
	2	Pass
	3	Pass
	4	Pass
	5	Pass
	6	Pass
	7	Pass
	8	Pass
Lot 3	1	Pass
	2	Pass
	3	Pass
	4	Pass
	5	Pass
	6	Pass
	7	Pass
	8	Pass

#### Thermal Cycle Air to Air

- -55 C to 125 C (dry)
- 2 Cycles Per Hour (CPH)
- Soak 5 to 10 Mins. at Tmin and Tmax
- 20 Cycles Total

#### Thermocouple Profile





<b>Date Created</b>	02/24/2011
<b>Created By</b>	Pletronics Engineering